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FORM PTO-1596
1-31-92

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HEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 43877-104

PATENTS ONLY

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):

Akio HOSAKA

Additional name(s) of conveying party(ies) attached? Yes

2. Name and address of receiving party(ies):

Name: Sodick Co., Ltd.

Address: 3-12-1, Nakamachidai

Tsuzuki-ku, Yokohama

Kanagawa 224-8522, Japan

Additional name(s) & address(es) attached? Yes

3. Nature of Conveyance:

Assignment

Merger

Security Agreement

Change of Name

Other To correct spelling of conveying party's name

Execution Date: April 11, 2000

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s).

09/514,848, filed February 28, 2000

B. Patent No(s).

Additional numbers attached? Yes

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Paul Devinsky

MCDERMOTT, WILL & EMERY

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: DC Zip: 20005

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

500417

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Paul Devinsky, 28,533

October 27, 2000

Name and Registration No. of Person Signing

Signature

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

12/04/2000 DNGUYEN 00000168 500417 09514848

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PATENT
REEL: 011292 FRAME: 0751

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

Akio HOSAKA

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

SODICK CO., LTD.

3-12-1, Nakamachidai

Tsuzuki-ku, Yokohama

Kanagawa 224-8522, Japan

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

APPARATUS FOR APPLYING TENSION TO A WIRE ELECTRODE

(a) for which an application for United States Letters Patent was filed on February 28, 2000, and identified by United States Serial No. 09/514,848; or


(b) for which an application for United States Letters Patent was executed on ,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR



DATE SIGNED

Apr. 11. 2000

Akio HOSAKA